

HRW0202B

Silicon Schottky Barrier Diode for Rectifying

HITACHI

Rev. 0
Apr. 1995

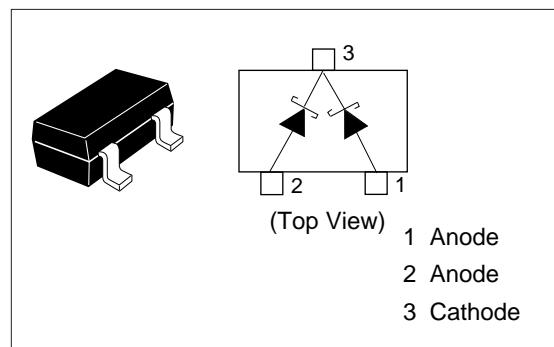
Features

- Low forward voltage drop and suitable for high efficiency rectifying.
- MPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HRW0202B	S18	MPAK

Pin Arrangement



Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$) *

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RRM}^{**}	20	V
Average forward current	I_o^{***}	200	mA
Non-Repetitive peak forward surge current	I_{FSM}^{****}	3	A
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

* Per one device

** See Fig.5

*** See Fig.4, Square wave, Duty (1/2), Two device total

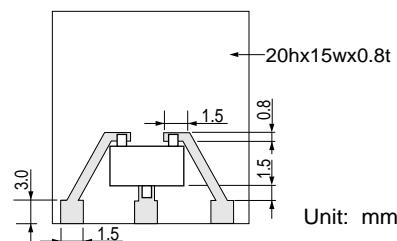
**** 10msec half sine wave 1 pulse

Electrical Characteristics ($T_a = 25^\circ\text{C}$) *

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	I_R	—	—	10	μA	$V_R = 20 \text{ V}$
Forward voltage	V_F	—	—	0.42	V	$I_F = 100 \text{ mA}$
Thermal resistance	$R_{th(j-a)}$	—	400	—	$^\circ\text{C/W}$	Polyimide substrate **

* Per one device

** Polyimide PCB



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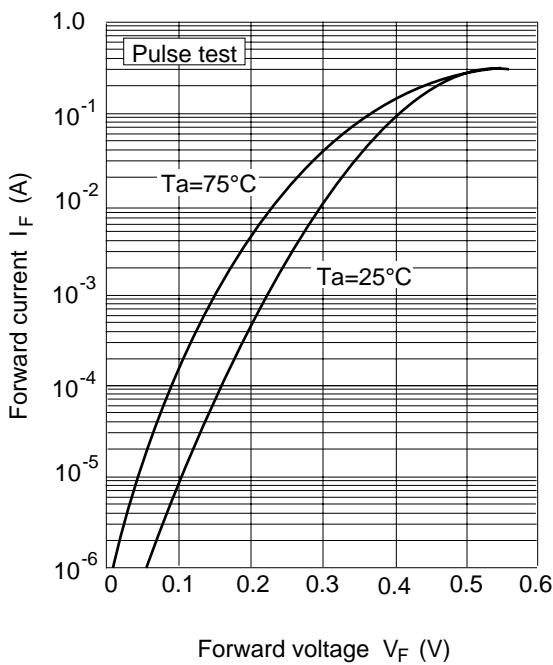


Fig.1 Forward current Vs.
Forward voltage

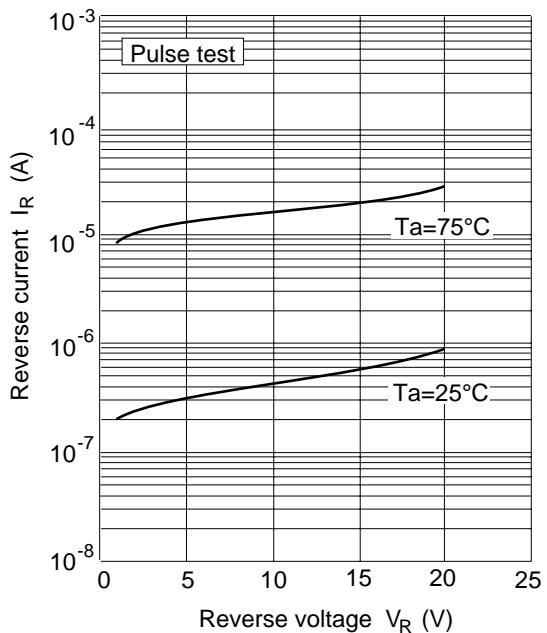


Fig.2 Reverse current Vs.
Reverse voltage

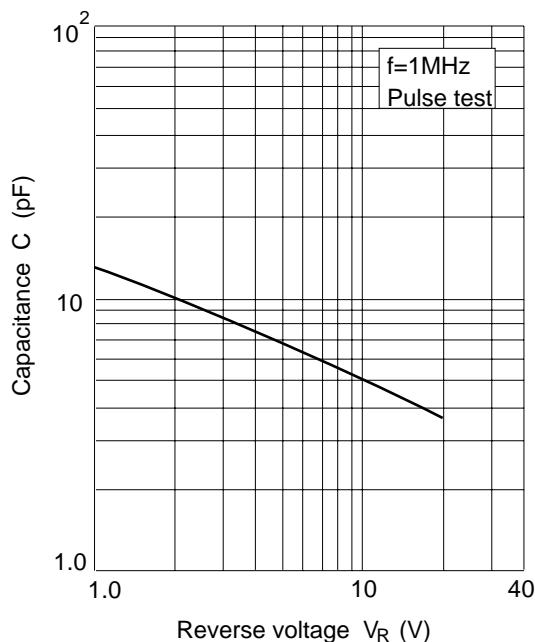
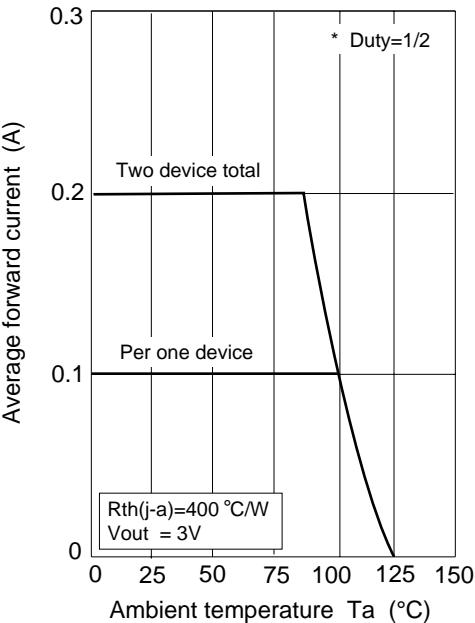
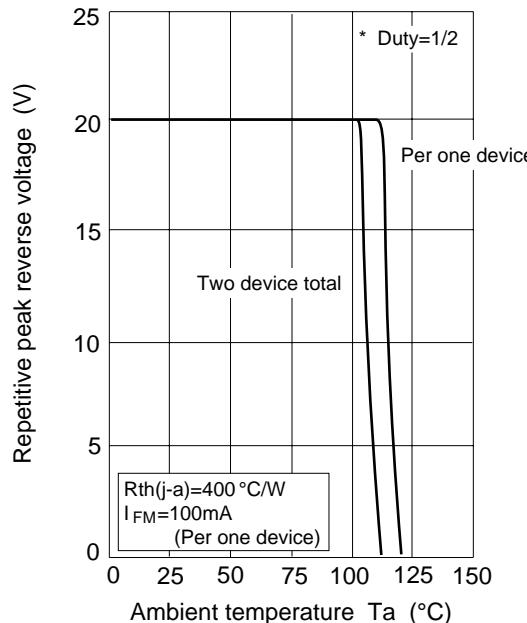


Fig.3 Capacitance Vs.
Reverse voltage



**Fig.4 Average forward current
Vs. Ambient temperature**



**Fig.5 Repetitive peak reverse voltage
Vs. Ambient temperature**

Package Dimensions

Unit: mm

